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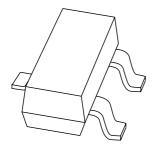
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Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



PBSS5240T 40 V, 2 A PNP low V_{CEsat} (BISS) transistor

Product data sheet Supersedes data of 2001 Oct 31 2004 Jan 15



40 V, 2 A PNP low V_{CEsat} (BISS) transistor

PBSS5240T

FEATURES

- Low collector-emitter saturation voltage
- · High current capability
- Improved device reliability due to reduced heat generation
- Replacement for SOT89/SOT223 standard packaged transistor.

APPLICATIONS

- · Supply line switching circuits
- · Battery management applications
- DC/DC converter applications
- · Strobe flash units
- Heavy duty battery powered equipment (motor and lamp drivers).

DESCRIPTION

PNP low V_{CEsat} transistor in a SOT23 plastic package. NPN complement: PBSS4240T.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾
PBSS5240T	ZF*

Note

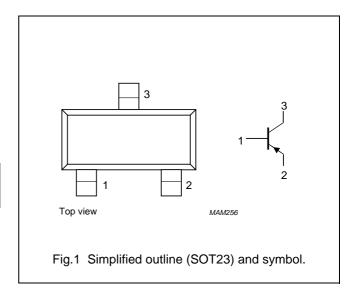
- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.
 - * = W: Made in China.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{CEO}	collector-emitter voltage	-40	V
I _C	collector current (DC)	-2	Α
I _{CM}	peak collector current	-3	Α
R _{CEsat}	equivalent on-resistance	<220	mΩ

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



ORDERING INFORMATION

TYPE NUMBER	PACKAGE			
TIPE NOMBER	NAME DESCRIPTION VERSION			
PBSS5240T	_	plastic surface mounted package; 3 leads SO		

40 V, 2 A PNP low V_{CEsat} (BISS) transistor

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-40	V
V _{CEO}	collector-emitter voltage	open base	_	-40	V
V _{EBO}	emitter-base voltage	open collector	_	- 5	V
I _C	collector current (DC)		_	-2	Α
I _{CM}	peak collector current		_	-3	Α
I _{BM}	peak base current		_	-300	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	-	300	mW
		T _{amb} ≤ 25 °C; note 2	-	480	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Device mounted on a printed-circuit board, single sided copper, tin plated, standard footprint.
- 2. Device mounted on a printed-circuit board, single sided copper, tin plated, mounting pad for collector 1 cm².

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air; note 1	417	K/W
		in free air; note 2	260	K/W

Notes

- 1. Device mounted on a printed-circuit board, single sided copper, tin plated, standard footprint.
- 2. Device mounted on a printed-circuit board, single sided copper, tin plated, mounting pad for collector 1 cm².

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

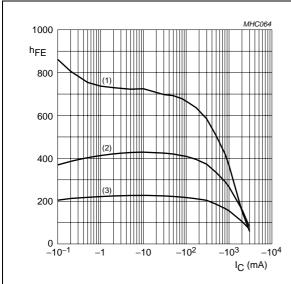
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -30 \text{ V}; I_E = 0$	_	_	-100	nA
		$V_{CB} = -30 \text{ V}; I_E = 0; T_j = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I _{BEO}	emitter-base cut-off current	$V_{EB} = -4 \text{ V}; I_C = 0$	_	_	-100	nA
h _{FE}	DC current gain	V _{CE} = −2 V				
		$I_{C} = -100 \text{ mA}$	300	450	_	
		$I_C = -500 \text{ mA}$	260	350	_	
		$I_C = -1 A$	210	290	_	
		$I_C = -2 A$	100	180	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -100 \text{ mA}; I_B = -1 \text{ mA}$	_	-55	-100	mV
		$I_C = -500 \text{ mA}; I_B = -50 \text{ mA}$	_	-70	-110	mV
		$I_C = -750 \text{ mA}; I_B = -15 \text{ mA}$	_	-140	-225	mV
		$I_C = -1 A$; $I_B = -50 \text{ mA}$	_	-140	-225	mV
		$I_C = -2 \text{ A}; I_B = -200 \text{ mA}$	_	-240	-350	mV
R _{CEsat}	equivalent on-resistance	$I_C = -500 \text{ mA}$; $I_B = -50 \text{ mA}$; note 1	_	160	<220	mΩ
V _{BEsat}	base-emitter saturation voltage	$I_C = -2 \text{ A}; I_B = -200 \text{ mA}$	_	_	-1.1	V
V _{BE(on)}	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V}; I_{C} = -100 \text{ mA}$	_	_	-0.75	V
f _T	transition frequency	$I_C = -100 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 100 MHz	100	200	_	MHz
C _c	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = I_e = 0;$ f = 1 MHz	-	23	28	pF

Note

1. Device mounted on a printed-circuit board, single sided copper, tin plated, standard footprint.

40 V, 2 A PNP low V_{CEsat} (BISS) transistor

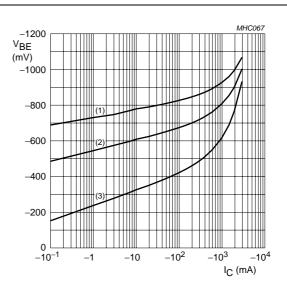
PBSS5240T



 $V_{CE} = -2V$.

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

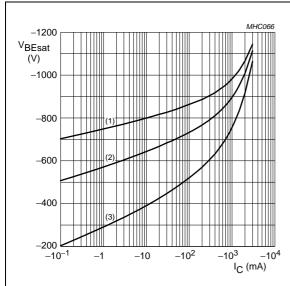
Fig.2 DC current gain as a function of collector current; typical values.



 $V_{CE} = -2V$.

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) T_{amb} = 25 °C.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

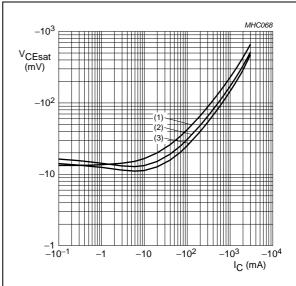
Fig.3 Base-emitter voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 20.$

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

Fig.4 Base-emitter saturation voltage as a function of collector current; typical values.



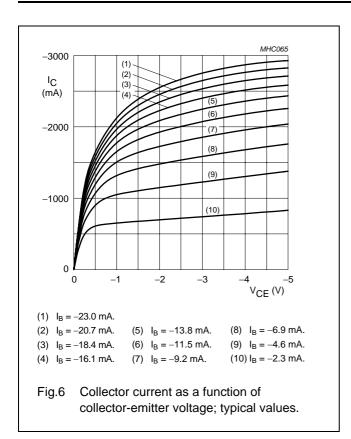
 $I_{\rm C}/I_{\rm B} = 20.$

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.5 Collector-emitter saturation voltage as a function of collector current; typical values.

40 V, 2 A PNP low V_{CEsat} (BISS) transistor

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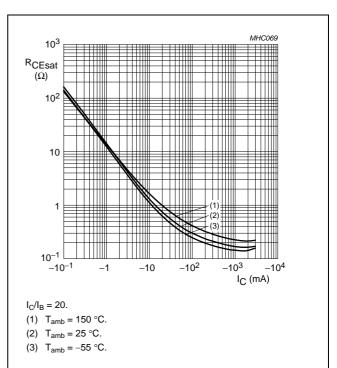


Fig.7 Equivalent on-resistance as a function of collector current; typical values.

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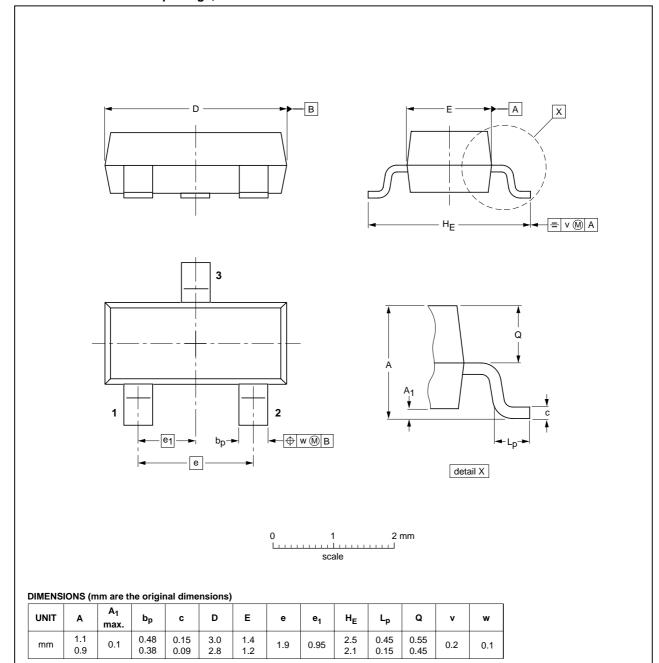
40 V, 2 A PNP low V_{CEsat} (BISS) transistor

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PACKAGE OUTLINE



SOT23



OUTLINE	REFERENCES		EUROPEAN	ICCUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION ISSUE DAT	
SOT23		TO-236AB				-04-11-04- 06-03-16

40 V, 2 A PNP low V_{CEsat} (BISS) transistor

PBSS5240T

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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